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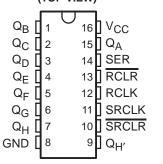
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- 8-Bit Serial-In, Parallel-Out Shift Registers With Storage
- Independent Direct Overriding Clears on Shift and Storage Registers
- Independent Clocks for Shift and Storage Registers
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

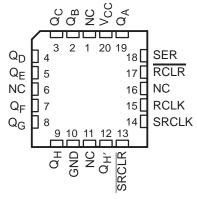
The 'LV594A devices are 8-bit shift registers designed for 2-V to 5.5-V V_{CC} operation.

These devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type

SN54LV594A . . . J OR W PACKAGE SN74LV594A . . . D, DB, NS, OR PW PACKAGE (TOP VIEW)



SN54LV594A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

storage register. Separate clocks (RCLK, SRCLK) and direct overriding clear (\overline{RCLR} , \overline{SRCLR}) inputs are provided on the shift and storage registers. A serial output ($Q_{H'}$) is provided for cascading purposes.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	0010 D	Tube of 40	SN74LV594AD	11/5044
	SOIC - D	Reel of 2500	SN74LV594ADR	LV594A
	SOP - NS	Reel of 2000	SN74LV594ANSR	74LV594A
-40°C to 85°C	SSOP – DB	Reel of 2000	SN74LV594ADBR	LV594A
		Tube of 90	SN74LV594APW	
	TSSOP - PW	Reel of 2000	SN74LV594APWR	LV594A
		Reel of 250	SN74LV594APWT	
	CDIP – J	Tube of 25	SNJ54LV594AJ	SNJ54LV594AJ
–55°C to 125°C	CFP – W	Tube of 150	SNJ54LV594AW	SNJ54LV594AW
	LCCC – FK	Tube of 55	SNJ54LV594AFK	SNJ54LV594AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54LV594A, SN74LV594A 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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description/ordering information (continued)

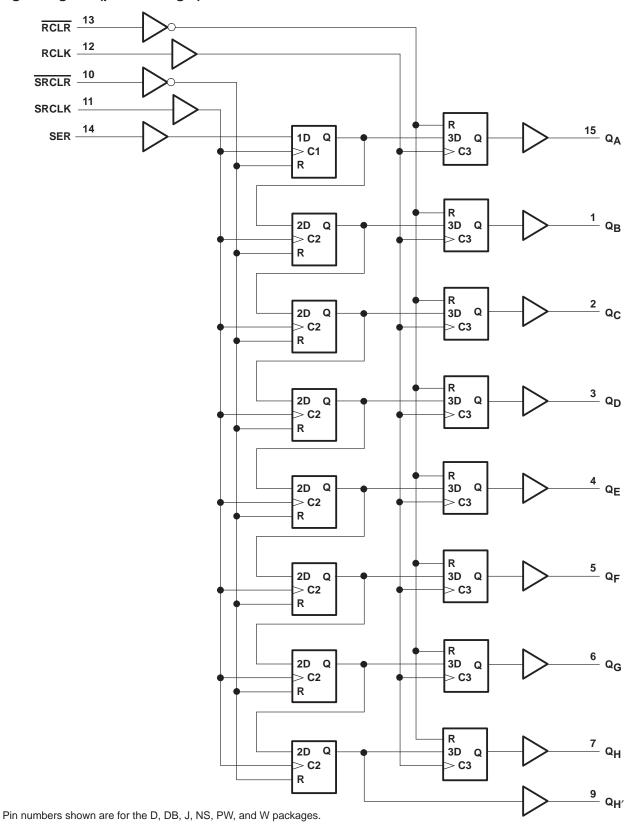
The shift-register (SRCLK) and storage-register (RCLK) clocks are positive-edge triggered. If the clocks are tied together, the shift register always is one clock pulse ahead of the storage register.

FUNCTION TABLE

_					
		INPUTS			FUNCTION
SER	SRCLK	SRCLR	RCLK	RCLR	FUNCTION
Х	Х	L	Х	Χ	Shift register is cleared.
L	1	Н	Х	Х	First stage of shift register goes low. Other stages store the data of previous stage, respectively.
Н	1	Н	Х	Х	First stage of shift register goes high. Other stages store the data of previous stage, respectively.
L	\downarrow	Н	Х	Х	Shift register state is not changed.
Х	Χ	X	X	L	Storage register is cleared.
Х	X	X	\uparrow	Н	Shift register data is stored in the storage register.
Х	Х	X	\downarrow	Н	Storage register state is not changed.



logic diagram (positive logic)





SN54LV594A, SN74LV594A 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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timing diagram SRCLK SER **RCLK** SRCLR RCLR \mathtt{Q}_{A} Q_{B} \mathtt{Q}_{C} $\mathtt{Q}_{\boldsymbol{D}}$ QΕ Q_{F} $\mathtt{Q}_{\boldsymbol{G}}$ $\mathtt{Q}_{\boldsymbol{\mathsf{H}}}$ $\textbf{Q}_{\textbf{H}'}$



SN54LV594A, SN74LV594A 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high-impedance or	
power-off state, V _O (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5 \text{ V}$
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	
Package thermal impedance, θ _{JA} (see Note 3): D package	
DB package	82°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			SN54L	.V594A	SN74L	.V594A	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
V	High level inner value	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} × 0.7		$V_{CC} \times 0.7$		V
VIH	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
V	Low level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
V _{IL}	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	V
		V _{CC} = 4.5 V to 5.5 V		V _{CC} ×0.3		$V_{CC} \times 0.3$	
٧ _I	Input voltage		0	5.5	0	5.5	V
VO	Output voltage		0	√Vcc	0	VCC	V
		V _{CC} = 2 V		-50		-50	μΑ
	Libely level autout access	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2	
ЮН	High-level output current	V _{CC} = 3 V to 3.6 V	30	-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	Q	-12		-12	
		V _{CC} = 2 V		50		50	μΑ
	Lave lavel autout aumant	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lor	Low-level output current	V _{CC} = 3 V to 3.6 V		6		6	mA
		V _{CC} = 4.5 V to 5.5 V		12		12	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		200	
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3 V \text{ to } 3.6 V$		100		100	ns/V
		V _{CC} = 4.5 V to 5.5 V		20		20	
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752	TEGE COMPLETIONS	.,	SN54L	V594A	SN74	LV594A	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP MAX	MIN	TYP M	X UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1		V _{CC} -0.1		
	$I_{OH} = -2 \text{ mA}$	2.3 V	2		2		
VOH	$I_{OH} = -6 \text{ mA}$	3 V	2.48	_	2.48		V
	$I_{OH} = -12 \text{ mA}$	4.5 V	3.8	TA	3.8		
	I _{OL} = 50 μA	2 V to 5.5 V		0.1		(.1
	I _{OL} = 2 mA	2.3 V	_ <	0.4		(.4 V
V _{OL}	I _{OL} = 6 mA	3 V	S	0.44		0.	
	I _{OL} = 12 mA	4.5 V	g	0.55		0.	55
lį	$V_I = 5.5 \text{ V or GND}$	0 to 5.5 V	Q.	±1			±1 μA
ICC	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		20			20 μΑ
l _{off}	V_I or $V_O = 0$ to 5.5 V	0		5			5 μΑ
Ci	V _I = V _{CC} or GND	3.3 V		3.5		3.5	pF

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timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			$T_A = 1$	25°C	SN54L	/594A	SN74L\	/594A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dulas duration	RCLK or SRCLK high or low	7		7.5		7.5		
t _W	Pulse duration	RCLR or SRCLR low	6		6.5	FIN	6.5		ns
		SER before SRCLK↑	5.5		5.5	F	5.5		
		SRCLK↑ before RCLK↑†	8		9 4	Ž.	9		
t _{su}	Setup time	SRCLR low before RCLK↑	8.5		9.5	,	9.5		ns
		SRCLR high (inactive) before SRCLK↑	6		6.8		6.8		
		RCLR high (inactive) before RCLK↑	6.7		7.6		7.6		
th	Hold time	SER after SRCLK↑	1.5		1.5		1.5		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			T _A =	25°C	SN54L	V594A	SN74L\	√594A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Dalam danation	RCLK or SRCLK high or low	5.5		5.5		5.5		
t _W	Pulse duration	RCLR or SRCLR low	5		5	FIN	5		ns
		SER before SRCLK↑	3.5		3.5	F	3.5		
		SRCLK↑ before RCLK↑†	8		8.5	2	8.5		
t _{su}	Setup time	SRCLR low before RCLK↑	8		9	,	9		ns
		SRCLR high (inactive) before SRCLK↑	4.2		4.8		4.8		
		RCLR high (inactive) before RCLK↑	4.6		5.3		5.3		
th	Hold time	SER after SRCLK↑	1.5		1.5		1.5		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A =	25°C	SN54L	V594A	SN74L	V594A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
	Delegation (fee	RCLK or SRCLK high or low	5		5		5		
t _W	Pulse duration	RCLR or SRCLR low	5.2		5.2	FW	5.2		ns
		SER before SRCLK↑	3		3	F	3		
		SRCLK↑ before RCLK↑†	5		5 (2	5		
t _{su}	Setup time	SRCLR low before RCLK↑	5		5	,	5		ns
		SRCLR high (inactive) before SRCLK↑	2.9		3.3		3.3		
		RCLR high (inactive) before RCLK↑	3.2		3.7		3.7		
th	Hold time	SER after SRCLK↑	2		2		2		ns

[†] This setup time allows the storage register to receive stable data from the shift register. The clocks can be tied together, in which case the shift register is one clock pulse ahead of the storage register.



switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

242445	FROM	то	LOAD	T,	4 = 25°C	;	SN54L	V594A	SN74L	/594A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	65*	80*		45*		45		N 41 1-
f _{max}			C _L = 50 pF	60	70		40		40		MHz
t _{PLH}	BOLK	0 0			6.4*	10.6*	1*	11.1*	1	11.1	
t _{PHL}	RCLK	Q_A-Q_H			6.3*	10.4*	1*	11.1*	1	11.1	
t _{PLH}	CDCI K	0			7.4*	12.1*	1*	12.8*	1	12.8	
t _{PHL}	SRCLK	$Q_{H'}$	C _L = 15 pF		7.2*	11.6*	1*	12.8*	1	12.8	ns
	RCLR	Q _A –Q _H			7.9*	12.7*	1* (13.6*	1	13.6	
^t PHL	SRCLR	Q _H ′			7.4*	11.9*	10	13.1*	1	13.1	
t _{PLH}	BOLK	0 0			9.5	14.1	Q1	14.6	1	14.6	
t _{PHL}	RCLK	Q_A-Q_H			10.8	15.5	<i>y</i> 1	17.2	1	17.2	
t _{PLH}	000114	•			10.6	15.7	1	16.5	1	16.5	
t _{PHL}	SRCLK	QH′	C _L = 50 pF		11.3	16.1	1	18.6	1	18.6	ns
+	RCLR	Q_A-Q_H			12.1	17.4	1	19	1	19	
^t PHL	SRCLR	$Q_{H'}$			11.6	16.5	1	18.6	1	18.6	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			т т								
DADAMETED	FROM	то	LOAD	T,	Վ = 25° C	;	SN54L\	/594A	SN74L	/594A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			C _L = 15 pF	80*	120*		70*		70		NAL I-
fmax			C _L = 50 pF	55	105		50		50		MHz
tPLH	DOLK	0 0			4.6*	8*	1*	8.5*	1	8.5	
tPHL	RCLK	Q_A – Q_H] [4.9*	8.2*	1*	8.8*	1	8.8	
t _{PLH}	00011	0			5.4*	9.1*	1*	9.7*	1	9.7	
tPHL	SRCLK	$Q_{H'}$	C _L = 15 pF		5.5*	9.2*	1*	9.9*	1	9.9	ns
	RCLR	Q _A –Q _H			6*	9.8*	1* <	10.6*	1	10.6	
^t PHL	SRCLR	Q _H ′			5.6*	9.2*	10	10*	1	10	
tPLH	DOLK	0 0			6.9	10.5	Q1	11.1	1	11.1	
tPHL	RCLK	Q_A – Q_H] [8.1	11.9	Q 1	13.1	1	13.1	
tPLH	00011]		7.7	11.7	1	12.4	1	12.4	
tPHL	SRCLK	QH′	C _L = 50 pF		8.4	12.5	1	13.9	1	13.9	ns
t =	RCLR	Q _A –Q _H] [9.1	13.1	1	14.4	1	14.4	
^t PHL	SRCLR	$Q_{H'}$			8.5	12.4	1	14	1	14	

 $^{^{\}star}$ On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	Δ = 25°C	;	SN54L\	/594A	SN74L	/594A	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			C _L = 15 pF	135*	170*		115*		115		N41.1-
f _{max}			C _L = 50 pF	120	140		95		95		MHz
t _{PLH}	DOLK	0 0			3.3*	6.2*	1*	6.5*	1	6.5	
t _{PHL}	RCLK	Q_A – Q_H]		3.7*	6.5*	1*	6.9*	1	6.9	
t _{PLH}	CDCI I	0			3.7*	6.8*	1*	7.2*	1	7.2	
t _{PHL}	SRCLK	$Q_{H'}$	C _L = 15 pF		4.1*	7.2*	1*	7.6*	1	7.6	ns
	RCLR	Q_A – Q_H			4.5*	7.6*	1* <	8.2*	1	8.2	
^t PHL	SRCLR	Q _H ′			4.1*	7.1*	10	7.6*	1	7.6	
t _{PLH}	DOLK	0 0			4.9	7.8	Q1	8.3	1	8.3	
t _{PHL}	RCLK	Q _A –Q _H]		5.8	8.9	% 1	9.7	1	9.7	
t _{PLH}	00011]		5.5	8.6	1	9.1	1	9.1	
t _{PHL}	SRCLK	QH′	$C_L = 50 pF$		6	9.2	1	10.1	1	10.1	ns
* ~	RCLR	Q_A-Q_H			6.6	10	1	10.7	1	10.7	
^t PHL	SRCLR	Q _H ′			6	9.2	1	10.1	1	10.1	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

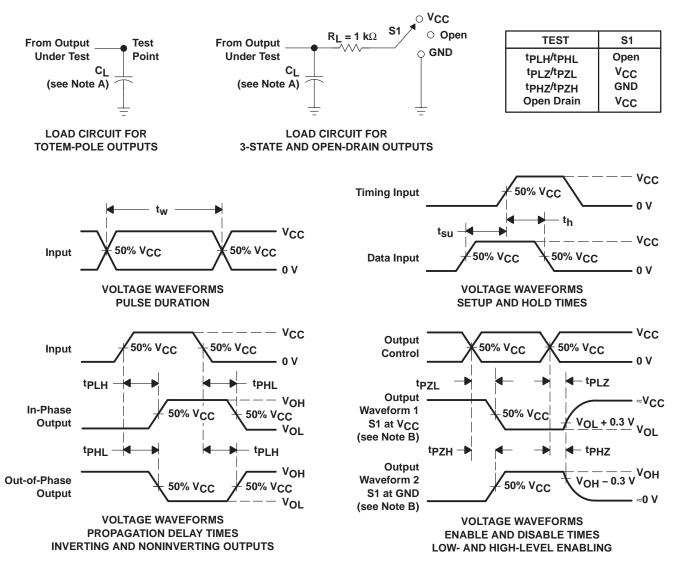
	DADAMETED	SN	74LV594	lA.	
	PARAMETER	MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic VOL		0.5	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		2.8		V
V _{IH(D)}	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER	TEST CONDITIONS	vcc	TYP	UNIT
C . Power discination conscitones	f = 10 MHz	3.3 V	93	pF
C _{pd} Power dissipation capacitance	I = IO MHZ	5 V	112	

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 3 \text{ ns}$, $t_f \le 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpz and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







17-May-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV594AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594ADBRE4	ACTIVE	SSOP	DB	16		TBD	Call TI	Call TI	-40 to 85		Samples
SN74LV594ADBRG4	ACTIVE	SSOP	DB	16		TBD	Call TI	Call TI	-40 to 85		Samples
SN74LV594ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594ADRE4	ACTIVE	SOIC	D	16		TBD	Call TI	Call TI	-40 to 85		Samples
SN74LV594ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594APWE4	ACTIVE	TSSOP	PW	16		TBD	Call TI	Call TI	-40 to 85		Samples
SN74LV594APWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594APWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples
SN74LV594APWTE4	ACTIVE	TSSOP	PW	16		TBD	Call TI	Call TI	-40 to 85		Samples
SN74LV594APWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV594A	Samples



PACKAGE OPTION ADDENDUM

17-May-2014

(1) The marketing status values are defined as follows:

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ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV594ADBR	SSOP	DB	16	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV594ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV594APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV594APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV594APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV594APWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV594ADBR	SSOP	DB	16	2000	367.0	367.0	38.0
SN74LV594ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LV594APWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74LV594APWR	TSSOP	PW	16	2000	364.0	364.0	27.0
SN74LV594APWRG4	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74LV594APWT	TSSOP	PW	16	250	367.0	367.0	35.0

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

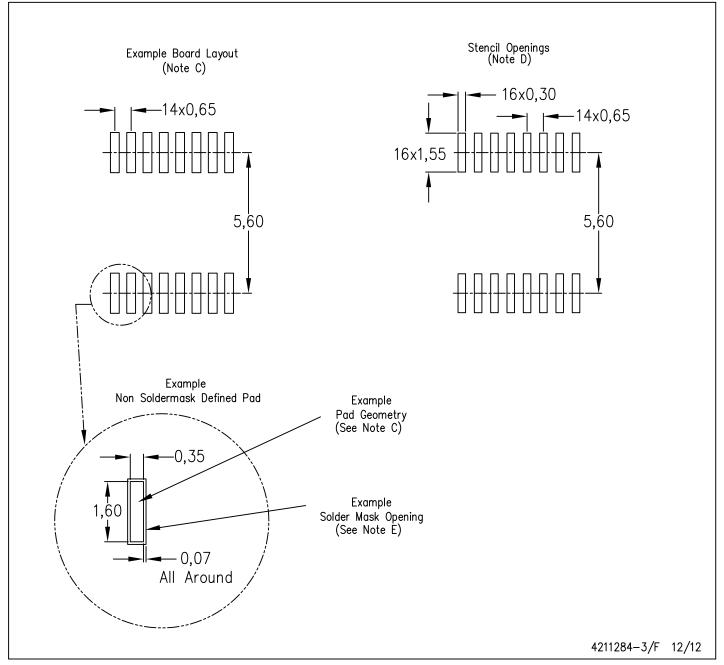


- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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